

P0150SD TSS

Rev.2.2

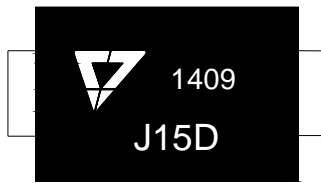
FEATURES:

- Low profile package.
- Low on-state voltage.
- Excellent capability of absorbing transient surge.
- Quick response to surge voltage (ns Level).
- Eliminates overvoltage caused by fast rising transients
- Moisture sensitivity level: Level 1.
- UL 497B item recognized. (File No.: E480698).
- IEC61000-4-2 (ESD) $\pm 30\text{kV}$ (air), $\pm 30\text{kV}$ (contact).
- Non degenerative.

ABSOLUTE MAXIMUM RATINGS ($V_A=25$, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Storage temperature range	T_{STG}	-60 to +150	
Operating junction temperature range	T_J	-40 to +125	
Repetitive peak pulse current@10/1000 s	I_{PP}	150	A

MARKING



J15D: Device Marking Code
1409: In ninth week, 2014

ELECTRICAL CHARACTERISTICS (Fig. 3) b A0 Uf

SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see FIG.2)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150
	-Temperature Max($T_{s(max)}$)	+200
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3 /sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 /sec. Max
Reflow	-Temperature(T_L) (Liquidus)	+217
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)
Time within 5 of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6 /sec. Max
Time 25 to Peak Temp (T_P)		8 min. Max
Do not exceed		+260

FIG.1: tr x td pulse waveform

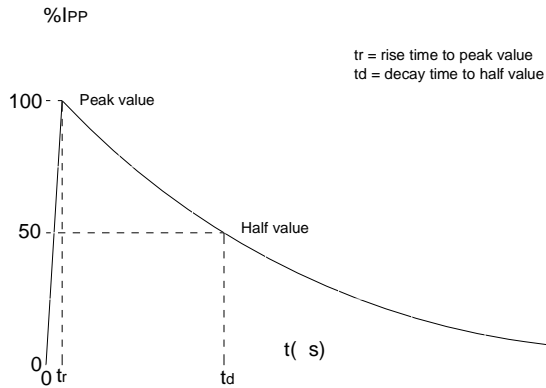


FIG.3: Normalized Vs change vs. junction temperature

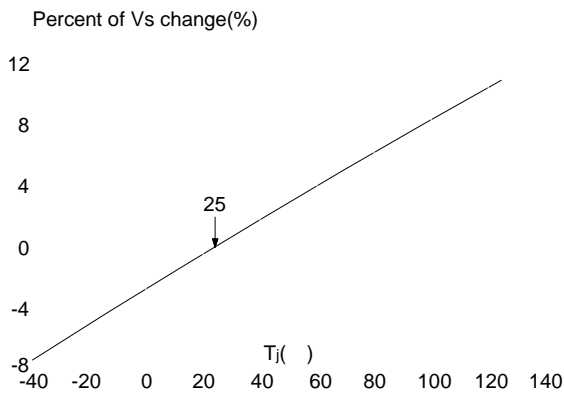


FIG.2: Reflow condition

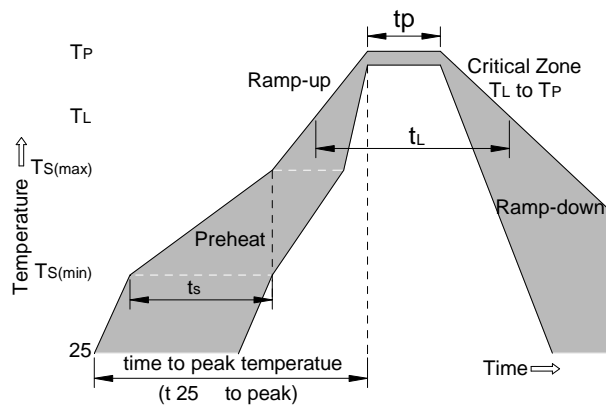
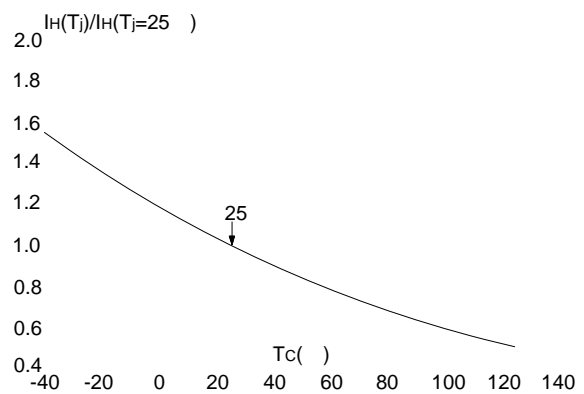
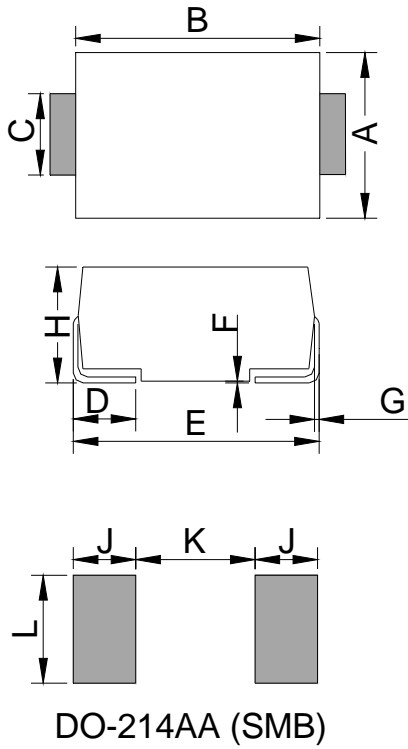


FIG.4: Normalized DC holding current vs. case temperature

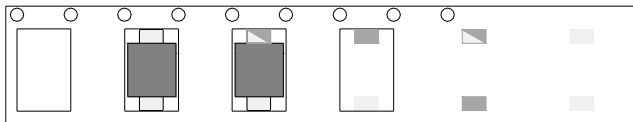


PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.30	3.94	0.130	0.155
B	4.30	4.80	0.169	0.189
C	1.90	2.20	0.075	0.087
D	0.95	1.52	0.037	0.060
E	5.20	5.60	0.205	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.10	2.40	0.083	0.094
J	2.20		0.087	
K		2.60		0.102
L	2.30		0.091	

TAPES AND REEL SPECIFICATION



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